

2SK2978

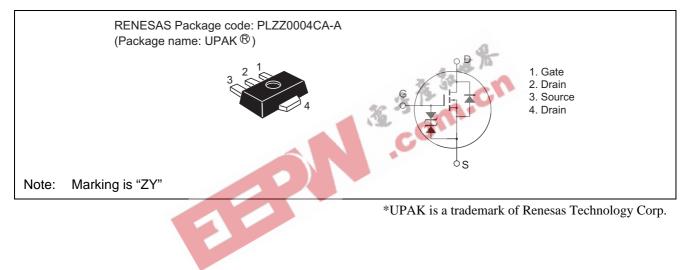
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G1060-0500 (Previous: ADE-208-659C) Rev.5.00 Sep.07,2005

Features

- Low on-resistance $R_{DS(on)}=0.09~\Omega \mbox{ typ. } (V_{GS}=4~V, \mbox{ } I_D=1.5~A) \label{eq:constraint}$
- Low drive current
- High speed switching
- 2.5 V gate drive devices.

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	20	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	ID	2.5	А
Drain peak current	Note1	5	А
Body-drain diode reverse drain current	I _{DR}	2.5	А
Channel dissipation	Pch ^{Note2}	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 $\mu s,$ duty cycle \leq 1 %

2. When using the alumina ceramic board (12.5 x 20 x 0.7 mm)

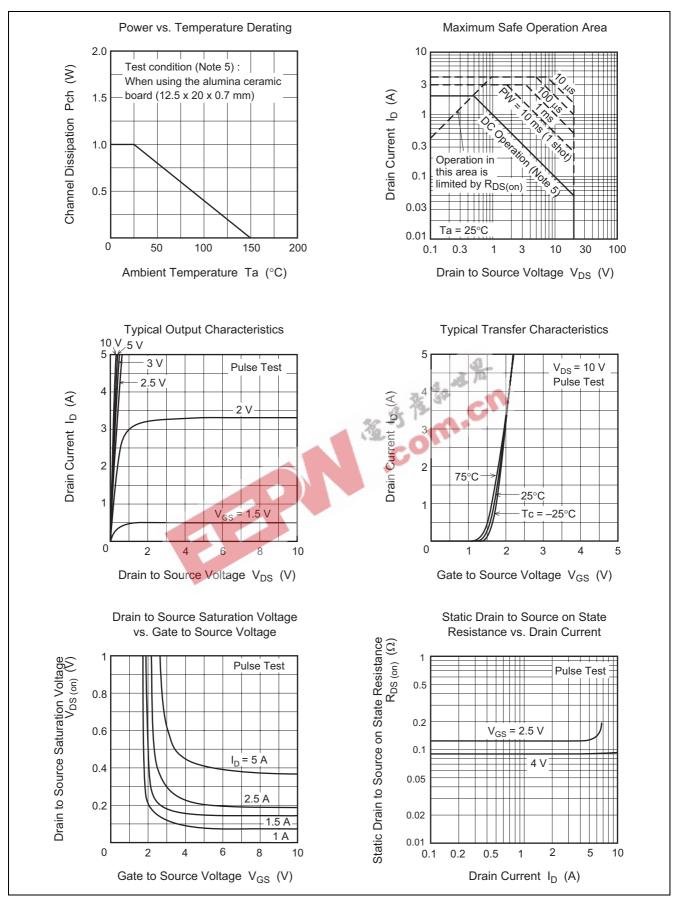
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	20	_	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±10	_	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	-		10	μΑ	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 8 \text{ V}, \text{ V}_{DS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	0.5	_	1.5	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	0.09	0.12	Ω	$I_{D} = 1.5 \text{ A}, \text{ V}_{GS} = 4 \text{ V}^{\text{Note3}}$
Static drain to source on state resistance	R _{DS(on)}	-	0.12	0.20	Ω	I_D = 1.5 A, V_{GS} = 2.5 V ^{Note3}
Forward transfer admittance	y fs	3.0	5.0	_	S	$I_D = 1.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss) -	260	—	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss		150		pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	75	_	pF	
Turn-on delay time	t _{d(on)}	—	15	_	ns	$V_{GS} = 4 V, I_D = 1.5 A,$
Rise time	tr		70		ns	$R_{L} = 6.67 \ \Omega$
Turn-off delay time	t _{d(off)}		55		ns	
Fall time	t _f		70		ns	
Body-drain diode forward voltage	V _{DF}	_	0.9	_	V	$I_F = 2.5 \text{ A}, V_{GS} = 0$
Body–drain diode reverse	t _{rr}	_	75	_	ns	$I_F = 2.5 \text{ A}, V_{GS} = 0$
recovery time						di _F / dt = 50 A/ µs

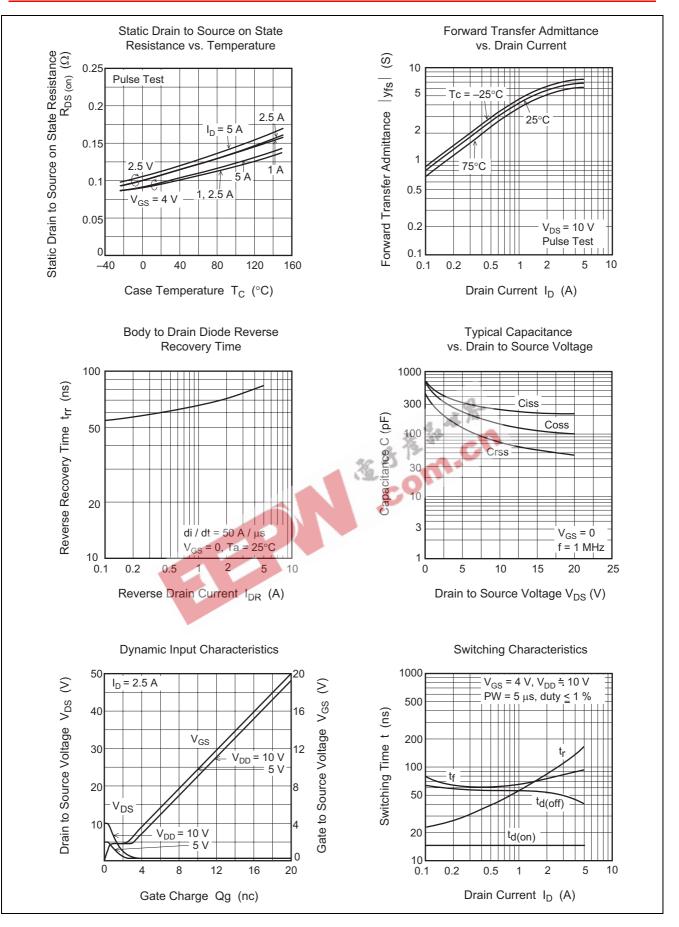
Note: 3. Pulse test



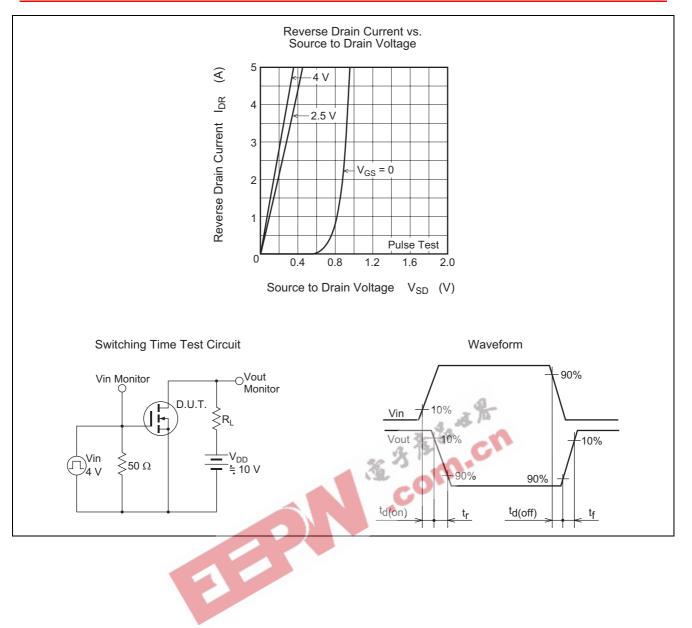
Main Characteristics





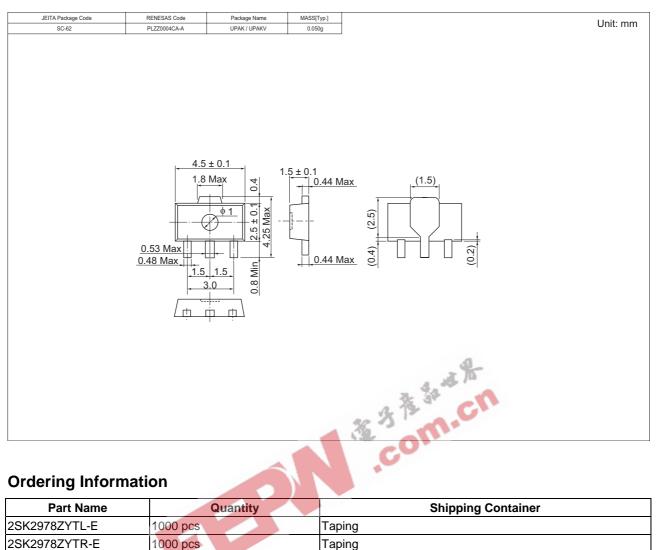








Package Dimensions



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